

## LINEAR TECHNOLOGY MATERIALS DECLARATION

LT8362EDD#TRPBF

(Engineering Calculation)

DFN 3mm X 3mm Exp. Pad

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**TOTAL MASS    0.023516**  
**(g):**

COMPONENT MATERIAL	VENDOR/ INDUSTRY NAMES	CONSTITUENT NAME	CAS NUMBER	CONSTITUENT MASS (g)	CONSTITUENT (PPM) OF MATERIAL	CONSTITUENT (PPM) OF TOTAL PKG.		
Active Device	Linear Technology	Silicon (Si)	7440-21-3	<b>0.001396</b>	<b>1000000</b>	<b>59362.9257812</b>		
Die Coat	Dow Corning	Silicone	69430-27-9	<b>0.000000</b>	<b>0</b>	<b>0</b>		
Lead Frame	Cu	Copper (Cu)	7440-50-8	0.009711	975000	412946.53125		
		Iron (Fe)	7439-89-6	0.000239	24000	10163.1367188		
		Phosphorus (P)	7723-14-0	0.000003	300	127.570747375		
		Zinc (Zn)	7440-66-6	0.000007	700	297.665100098		
		Nickel (Ni)	7440-02-0	0.000000	0	0		
		Silicon (Si)	7440-21-3	0.000000	0	0		
		Magnesium (Mg)	7439-95-4	0.000000	0	0		
		Tin (Sn)	7440-31-5	0.000000	0	0		
		<b>Lead Frame Total:</b>				<b>0.009960</b>	<b>1000000</b>	<b>423534.90625</b>
Plating	PMI	Exter. Plating Pb	7439-92-1	0.000000	0	0		
		Exter. Plating Sn	7440-31-5	0.000455	1000000	19363.6523438		
		<b>External Plating Total:</b>				<b>0.000455</b>	<b>1000000</b>	<b>19363.6523438</b>
		Inter. Plating Ni	7440-02-0	0.000000	0	0		
		Inter. Plating Ag	7440-22-4	0.000225	1000000	9567.80664062		
		<b>Internal Plating Total:</b>				<b>0.000225</b>	<b>1000000</b>	<b>9567.80664062</b>
Die Attach	ELECTRICALLY CONDUCTIVE ADHESIVE	Silver (Ag)	7440-22-4	0.000720	750000	30616.9804688		
		Tin (Sn)	7440-31-5	0.000000	0	0		
		Lead (Pb)	7439-92-1	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.000000	0	0		
		Indium (In)	7440-74-6	0.000000	0	0		
		Metal Oxide		0.000000	0	0		
		Antimony (Sb)	7440-36-0	0.000000	0	0		
		Resin (EP)		0.000240	250000	10205.6601562		
		<b>Die Attach Total:</b>				<b>0.000960</b>	<b>1000000</b>	<b>40822.640625</b>
Encapsulation	MULTI-AROMATIC RESIN Br/Sb FREE	Resin (EP)		0.001362	130000	57917.1210938		
		Bromine (Br)	40039-93-8	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.009013	860000	383265.0625		
		Antimony Trioxide (Sb2O3)	1309-64-4	0.000000	0	0		
		Metal Hydroxide		0.000000	0	0		
		Carbon Black (C)	1333-86-4	0.000105	10000	4464.97607422		
		<b>Encapsulation Total:</b>				<b>0.010480</b>	<b>1000000</b>	<b>445647.15625</b>
Bond Wire Estimated	AFW/TANAKA/ Kn	Gold (Au)	7440-57-5	<b>0.000040</b>	<b>1000000</b>	<b>1700.94335938</b>		

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